

SHIELDING

CONDUCTIVE FOAM

Features:

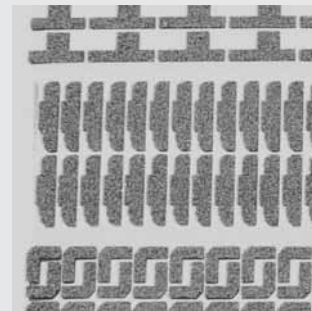
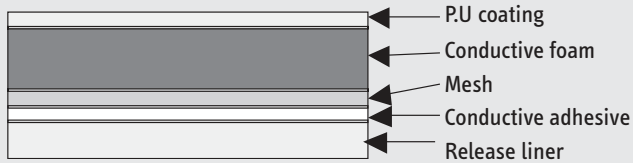
Kitagawa Conductive Foam provides excellent X,Y and Z axis conductivity and offers very good shielding and grounding effectiveness.

The Foam is designed for low-cycling applications such as I/O-shielding and is easy to fix, cut and punch to customers specification.



Product No: DECF - 000P

Structure:



Characteristics:

Item		Standard	Reference
Material	P.U. Coating	Polymer resin : Polyurethane (conductive)	
	Conductive foam	Polyurethane foam (Copper and Nickel Plated)	
	Mesh	Polyester woven mesh with Copper and Nickel plated	
	Adhesive	Both side conductive adhesive	
	Release Liner	CP paper (avg 70 μm)	
Conductive adhesive resin composition		Acrylic ester polyol copolymer + Nickel powder	
Lead (Pb) content	Not detected	ISO 6101-2	Analytical instrument : AAS
Cadmium (Cd) content	Not detected	EN 1122	Analytical instrument : ICP
Mercury (Hg) content	Not detected	ISO 3856/7	Analytical instrument : AAS
Chromium VI (Cr ⁶⁺) content	Not detected	ISO 3856/5	UV-Vis. Spectrophotometer
Temperature Limit (°C)	-10 ~ 60		
Adhesive Strength (180° peel * gf / 25mm)	800 ↑	26°C * 60% R.H.	SUS 304 Plate 30min, 300mm/min
Holding Strength (sec)	3,600 ↑		PET film (25 μm), 40°C, 500g
Volume conductivity (Ω / sq)	0,2 ↓		EMQI-1031 (Inch / 0.5Kgf)

Part list:

Part No	Thickness (mm)	Width (mm)	Length (m)
DECF-005P	0.5+/-0.2	300	50m / roll
DECF-008P	0.8+/-0.2	300	50m / roll
DECF-010P	1.0+/-0.2	300	50m / roll
DECF-013P	1.3+/-0.2	300	50m / roll
DECF-015P	1.5+/-0.2	300	50m / roll
DECF-020P	2.0+/-0.3	500	50m / roll
DECF-040P	4.0+/-0.3	500	50m / roll